



# MULTILAYER CERAMIC CAPACITORS

Ultra-small Series (6.3V to 50V)

01005 Size

NP0, X7R & X5R Dielectrics

Halogen Free & RoHS Compliance

\*Contents in this sheet are subject to change without prior notice.



### **1. INTRODUCTION**

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

01R5 MLCC is performed by high precision technology achieve high capacitance in unit size and ensure the stability and reliability of products.

### 2. FEATURES

- a. High capacitance in unit size.
- b. High precision dimensional tolerances.
- c. Suitable used in high-accuracy automatic mounting machine.

### **3. APPLICATIONS**

- a. Miniature microwave module.
- b. Portable equipments (ex. Mobile phone, PDA).
- c. High frequency circuits.

### 4. HOW TO ORDER

<u>01R5</u>	<u>N</u>	<u>100</u>	<u>C</u>	<u>160</u>	<u>C</u>	I	
<u>Size</u>	<b>Dielectric</b>	Capacitance	<u>Tolerance</u>	Rated voltage	<u>Termination</u>	Packaging	
Inch (mm) 01R5 = 01005 (0402)	<b>N</b> =NP0 (C0G) <b>B</b> =X7R <b>X</b> =X5R	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 0R5=0.5pF 1R0=1.0pF 100=10x10 <sup>0</sup>	A=±0.05pF B=±0.1pF C=±0.25pF D=±0.5pF F=±1% G=±2% J=±5% K=±10% M=±20%	Two significant digits followed by no, of zeros. And R is in place of decimal point. <b>6R3</b> =6.3 VDC <b>100</b> =10 VDC <b>160</b> =16 VDC <b>250</b> =25 VDC	<b>C</b> =Cu/Ni/Sn	T=7" reeled	
		=10pF	Chnolog	<b>500</b> =50 VDC			
ECHNOLOGY CORPORATION. HULL							

Copyright © by Walsin Technology Corporation. | All rights reserved.

# **5. EXTERNAL DIMENSIONS**

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Syı	nbol	M <sub>B</sub> (mm)	
01R5 (0402)	0.40±0.02	0.20±0.02	0.20±0.02	V	0.10±0.03	
* Reflow soldering only						

Reflow soldering only



# **6. GENERAL ELECTRICAL DATA**

Size		01R5			
Dielectric	NP0	X7R	X5R		
Capacitance*	0.2pF to 100pF	100pF to 1000pF	1000pF to 0.1µF		
Capacitance tolerance**	Cap≤5pF: A (±0.05pF), B (±0.1pF), C (±0.25pF) 5pF <cap<10pf: C (±0.25pF), D (±0.5pF) Cap≥10pF: F (±1%), G (±2%), J (±5%)</cap<10pf: 	K (±10%), M (±20%)			
Rated voltage (WVDC)	16V, 25V, 50V	10V 213	6.3V, 10V		
DF / Q <sup>#1</sup>	Cap<30pF, Q≥400+20C Cap≥30pF, Q≥1000	≤5 %	≤10 %		
Insulation resistance at Ur	≥10GΩ or RxC≥500Ω*F	whichever is less	RxC≥50Ω*F		
Operating temperature	-55 to +125℃	-55 to +125°C	-55 to +85℃		
Capacitance change	±30ppm ±15%				
Termination	Ni/Sn (lead-free termination)				

NP0: Apply 0.5~5Vrms, 1.0MHz±10% at the condition of 25°C ambient temperature.

X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 25°C ambient temperature. X5R: Apply 0.5±0.2Vrms or 1.0±0.2Vrms<sup>#1</sup>, 1.0kHz±10%, at the condition of 25°C ambient temp erature.

\*\* Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.

#1: Please refer to "RELIABILITY TEST CONDITIONS AND REQUIREMENTS" for detail

Copyright © by Walsin Technology Corporation. | All rights reserved.

Approval Sheet



## 7. CAPACITANCE RANGE

	SIZE		01R5	
	DIELECTRIC		NP0	
RAT	ED VOLTAGE (VDC)	16	25	50
	0.2pF (0R2)	V	V	V
	0.3pF (0R3)	V	V	V
	0.4pF (0R4)		V	V
	0.5pF (0R5)		V	V
	1.0pF (1R0)		V	V
	1.5pF (1R5)	V	V	V
	2.0pF (2R0)	V	V	V
	3.0pF (3R0)		V	V
	4.0pF (4R0)	V	V	V
	5.0pF (5R0)		V	V
	6.0pF (6R0)	V	V	V
ő	7.0pF (7R0)	V	V	V
tar	8.0pF (8R0)	V	V	V
aci	9.0pF (9R0)	V	V	V
Capacitance	10pF (100)	V	V	V
ပ	12pF (120)	V	V	V
	15pF (150)	V	V	V
	18pF (180)	V	V	V
	22pF (220)	V	V	V
	27pF (270)	V	V	V
	33pF (330)	<u> </u>	V	V
	39pF (390)	V	V	VE
	47pF (470)	<u> </u>	V	No M
	56pF (560)	<u>V</u>	V	V
	68pF (680)	<u> </u>	V	V -
	82pF (820)	<u>V</u>	V	N N
	100pF (101)	V	VTTL	

SIZE		01R5
	DIELECTRIC	X7R
RA	TED VOLTAGE (VDC)	10
	100pF (101)	V
Capacitance	150pF (151)	V
itaı	220pF (221)	V
oac	330pF (331)	V
Cap	470pF (471)	V
	1,000pF (102)	V

	SIZE	01	R5
	DIELECTRIC	X	5R
RA	TED VOLTAGE (VDC)	6.3	10
	1,000pF (102)	V	V
	1,500pF (152)		V
	2,200pF (222)		V
	3,300pF (332)		V
ce	4,700pF (472)		V
tan	6,800pF (682)		V
Capacitance	0.010µF (103)	V	V
ap	0.015µF (153)		
Ü	0.022µF (223)	V	
	0.033µF (333)	V	
	0.047µF (473)	V	
	0.068µF (683)		
	0.10µF (104)	V	

1. The letter in cell is expressed the symbol of product thickness.

 For more information about products with special capacitance or other data, please contact WTC local representative.

# 8. PACKAGING DIMENSION AND QUANTITY

Size	Thickness (mm)/Sumh		Paper tape 7" reel 13" reel		
5126	Thickness (mm)/Symbo	UI			
01R5 (0402)	0.20±0.02	V	20,000	-	

Unit: pieces

Copyright © by Walsin Technology Corporation. | All rights reserved.



# 9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	ltem	Test Condition	Requirements		
1.	Visual and Mechanical		* No remarkable defect. * Dimensions to conform to individual specification sheet.		
2.	Capacitance	Class I: NP0	* Shall not exceed the limits given in the detailed spec.		
3.	Q/ D.F. (Dissipation Factor)	Cap≤1000pF, 0.5~5Vrms, 1MHz±10% Cap>1000pF, 1.0±0.2Vrms, 1KHz±10% Class II: , X7R & X5R(≥10V) 1.0±0.2Vrms, 1KHz±10% Class II: , X5R(≤6.3V) 0.5±0.2Vrms, 1kHz±10% *Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp .	* NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C X7R: ≤5.0 % X5R: ≤10 %		
4.	Dielectric Strength	<ul> <li>* To apply voltage (≤100V) 250%.</li> <li>* Duration: 1 to 5 sec.</li> <li>* Charge and discharge current less than 50mA.</li> </ul>	* No evidence of damage or flash over during test.		
5.	Insulation Resistance	To apply rated voltage for max. 120 sec.	* NP0, X7R: ≥10GΩ or RxC≥500Ω-F whichever is smaller. X5R: RxC≥50Ω-F		
6.	Temperature	With no electrical load.			
	Coefficient	T.C. Operating Temp	T.C. Capacitance Change		
		NPO -55~125°C at 25°C	NPO Within ±30ppm/℃		
		X7R -55~125°C at 25°C	X7R Within ±15%		
		*Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24±2 hrs at room temp. *Measurement voltage for Class II Cap≤0.01µF: 0.5V Cap>0.01µF: 0.2V PASSIVE SYSTEM AL			
7.	Adhesive Strength of Termination	* Pressurizing force : 1N * Test time: 10±1 sec.	* No remarkable damage or removal of the terminations.		
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.		
	Resistance	<ul> <li>* Total amplitude: 1.5mm</li> <li>* Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.)</li> <li>* Before initial measurement (Class II only):</li> <li>To apply de-aging at 150°C for 1hr then set for 24± 2 hrs at room temp.</li> <li>* Cap./DF(Q) Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.</li> </ul>	* Cap change and Q/D.F.: To meet initial spec.		
9.	Solderability	* Solder temperature: 235±5℃	95% min. coverage of all metalized area.		
10.	* Dipping time: 2±0.5 sec.      * Dipping time: 2±0.5 sec.      * The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second unt the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec.     * Before initial measurement (Class II only):     To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.     * Measurement to be made after keeping at room temp. for 24±2 hrs.		<ul> <li>* No remarkable damage.</li> <li>* Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5%</li> <li>X5R: within ±25.0%</li> <li>(This capacitance change means the change of capacitance unde specified flexure of substrate from the capacitance measured before the test.)</li> </ul>		



No.	ltem	Test Condition		Requirements	
11.	Resistance to	* Solder temperature: 260±5℃		* No remarkable damage.	
	Soldering Heat	<ul> <li>Dipping time: 10±1 sec</li> <li>Preheating: 120 to 150°C for 1 minute before imme rse the capacitor in a eutectic solder.</li> </ul>		* Cap change: NP0: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5%	
	* Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp . * Cap. / DF(Q) / I.R. Measurement to be made after de-aging		X5R: within ±15.0% Q/D.F., I.R. and dielectric strength: To meet initial requirements. * 25% max. leaching on each edge.		
12.	Temperature	at 150°C for 1hr then set for 24±2 hrs at room ter * Conduct the five cycles according to the tempe		* No remarkable damage.	
		time.		* Cap change:	
		Step Temp. (°C) Tim	ne (min.)	NP0: within ±2.5% or ±0.25pF whichever is larger.	
		1 Min. operating temp. +0/-3 30-		X7R: within ±7.5% X5R: within ±15.0%	
		2 Room temp. 2~3		* Q/D.F., I.R. and dielectric strength: To meet initial requirements.	
		3         Max. operating temp. +3/-0         30:           4         Room temp.         2~3			
		* Before initial measurement (Class II only): To a at 150°C for 1hr then set for 24±2 hrs at room ter * Cap. / DF(Q) / I.R. Measurement to be made a	pply de-aging np . fter de-aging		
13.	Humidity	at 150℃ for 1hr then set for 24±2 hrs at room ter * Test temp.: 40±2℃	np.	* No remarkable damage.	
		* Humidity: 90~95% RH		* Cap change:	
		* Test time: 500+24/-0hrs.	2	NP0: within ±5.0% or ±0.5pF whichever is larger.	
		* Before initial measurement (Class II only): To a at 150°C for 1hr then set for 24±2 hrs at room ter	1 - 21	X7R: within ±12.5% X5R: within ±25.0%	
		* Cap. / DF(Q) / I.R. Measurement to be made a		* Q/D.F. value:	
		at 150℃ for 1hr then set for 24±2 hrs at room ter	败历之	NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C Cap<10pF; Q≥200+10C	
		HHI -		X7R: ≤7.5%	
		tter		X5R: ≤20% * I.R.:	
			954	NP0, X7R: ≥1GΩ or RxC≥50Ω-F whichever is smaller. X5R: RxC≥10Ω-F.	
14.		* Test temp.: 40±2°C	SYSTEM ALL	* No remarkable damage.	
	(Damp Heat)	* Humidity: 90~95%RH * Test time: 500+24/-0 hrs.		* Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger.	
		* To apply voltage : rated voltage.		X7R: within $\pm 15.0\%$	
		* Before initial measurement (Class II only): To a	pply de-aging	X5R: within ±25.0%	
		at 150℃ for 1hr then set for 24±2 hrs at room ter		Q/D.F. value:	
		* Cap. / DF(Q) / I.R. Measurement to be made a at 150°C for 1hr then set for 24±2 hrs at room to		NP0: Cap≥30pF, Q≥200; Cap<30pF; Q≥100+10/3C X7R; ≤7.5%	
			OGV CORPOR	X5R: ≤20%	
				* I.R.:	
				NP0, X7R: ≥500MΩ or RxC≥25Ω-F whichever is smaller. X5R: RxC≥5Ω-F.	
15.	High Temperature	* Test temp.: NP0, X7R: 125±3℃			
	Load (Endurance)	X5R: 85±3℃ * To apply voltage:			
	(Endurance)	(1) NP0, X7R : 200% of rated voltage			
		(2) X5R: 10V : 150 % of rated voltage		* No remarkable damage.	
		6.3V : 100 % of rated voltage * Test time: 1000+24/-0 hrs.		* Cap change: NP0: within ±3.0% or ±0.3pF whichever is larger.	
		* Before initial measurement (Class II only): To a	pply de-aging	X7R: within ±12.5%	
		at 150°C for 1hr then set for $24\pm 2$ hrs at room ter		X5R: within ±25.0%	
		* Cap. / DF(Q) / I.R. Measurement to be made af 150°C for 1hr then set for 24±2 hrs at room tem	ter de-aging at		
		** De-rating conditions:		NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C Cap<10pF; Q≥200+10C	
			-	X7R: ≤7.5%	
			c	X5R: ≤20%	
		Boole Contraction of the second	c	* I.R.: NB0_X7B: >1C0 or BxC>500 E which over is smaller	
		eo		NP0, X7R: ≥1GΩ or RxC≥50Ω-F whichever is smaller. X5R: RxC≥10Ω-F.	
		0 25 50 75 100 125 150 Temperature at Product (*C)			
	1				

### Page 6 of 8

ASC\_Ultra Small\_(01R5)\_026F\_AS

Copyright © by Walsin Technology Corporation. | All rights reserved.

### **APPENDIXES**

### Tape & reel dimensions



- j. Order bar code including series and item numbers
- k. Serial number of label

**Approval Sheet** 

#### Constructions

No.	Name		NP0	X7R, X5R
1	Ceramic material		CaZrO₃ based	BaTiO₃ based
2	Inner electrode		Ni	
3		Inner layer	Cu	
4	Termination	Middle layer	Ni	
5		Outer layer	Sn (Matt)	



Approval Sheet

### Storage and handling conditions

(1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.

(2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

#### Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of  $N_2$  within oven are recommended.

>/

SYSTEM ALLIANCE

